IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of	:	
Kazumi MATSUSHIGE et al.	:	
Serial No. NEW	:	**Attn: APPLICATION BRANCH**
Filed January 20, 2004	:	Attorney Docket No. 2004-0076

METHOD OF SOLDERING LEAD-FREE SOLDER, AND JOINED OBJECT SOLDERED BY THE SOLDERING METHOD
(Rule 1.53(b) Divisional of Serial No. 10/009,168, Filed December 7, 2001)

THE COMMISSIONER IS AUTHORIZED TO CHARGE ANY DEFICIENCY IN THE FEE FOR THIS PAPER TO DEPOSIT ACCOUNT NO. 23-0975.

PRELIMINARY AMENDMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Kindly amend the above-identified U.S. patent application as follows: